



**Materials Declaration**

<b>Package</b>	QSOP
<b>Body Size/Pitch</b>	150 mils
<b>LeadCount</b>	16
<b>Option</b>	Pb-Free

Molding Compound			
Item	% of Compound	Weight (g)	PPM
SiO2 Filler	85	3.66 E-02	474659
Epoxy resin	10	4.30 E-03	55842
Phenol Resin	3	1.29 E-03	16753
Antimony_Sb2O3	1.5	6.46 E-04	8376
Brominated Resin	0.5	2.15 E-04	2792
Subtotal		4.30 E-02	558422

Molding Compound		
Item	PPM	Method
Pb	Not Detected	EPA Method 3051A/3052. ICP-OES.
Cd	Not Detected	EPA Method 3051A/3052. ICP-OES.
Hg	Not Detected	EPA Method 3051A/3052. ICP-OES.
Cr+6	Not Detected	EPA Method 3060A& 7196A. UV-VIS.
PBB	Not Detected	EPA Method 3540C/3550C. GC/MS.
PBDE	Not Detected	EPA Method 3540C/3550C. GC/MS.

Leadframe			
Item	% of Leadframe	Weight (g)	PPM
Cu	97.5	2.99 E-02	388305
Fe	2.35	7.21 E-04	9359
P	0.03	9.21 E-06	119
Zn	0.12	3.68 E-05	478
Subtotal		3.07 E-02	398261

Die Attach Paste		
Item	PPM	Method
Pb	Not Detected	EPA Method 3051A/3052. ICP-OES.
Cd	Not Detected	EPA Method 3051A/3052. ICP-OES.
Hg	Not Detected	EPA Method 3051A/3052. ICP-OES.
Cr+6	Not Detected	EPA Method 3060A& 7196A. UV-VIS.
PBB	Not Detected	EPA Method 3540C/3550C. GC/MS.
PBDE	Not Detected	EPA Method 3540C/3550C. GC/MS.

Internal Leadframe Plating			
Item	% of Plating	Weight (g)	PPM
Ag	100	4.45 E-04	5773

External Leadframe Plating			
Item	% of Plating	Weight (g)	PPM
Sn	100	8.64 E-04	11204

Bond Wires			
Item	% of Wire	Weight (g)	PPM
Au	99.99	4.20 E-04	5448

Chip			
Item	% of Chip	Weight (g)	PPM
Si	100	1.30 E-03	16823

Die Attach			
Item	% of Die Attach	Weight (g)	PPM
Ag Filler	75	2.35 E-04	3051
Resin	25	7.84 E-05	1017
Subtotal		3.14 E-04	4068

Package Totals	
Weight (g)	PPM
7.71 E-02	1000000

Note: The information provided in this declaration are true to the best of ADI's knowledge  
 ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.



ADI Proprietary



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### Molding Compound

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### Die Attach Paste

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### Internal Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Ag	100	4.45 E-04	5773

### External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	85	7.34 E-04	9523
Pb	15	1.30 E-04	1681
Subtotal		8.64 E-04	11204

### Bond Wires

Item	% of Wire	Weight (g)	PPM
Au	99.99	4.20 E-04	5448

### Chip

Item	% of Chip	Weight (g)	PPM
Si	100	1.30 E-03	16823

### Die Attach

Item	% of Die Attach	Weight (g)	PPM
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